

# SOT441A

studless ceramic package; 4 leads

8 February 2016

Package information

## 1. Package summary

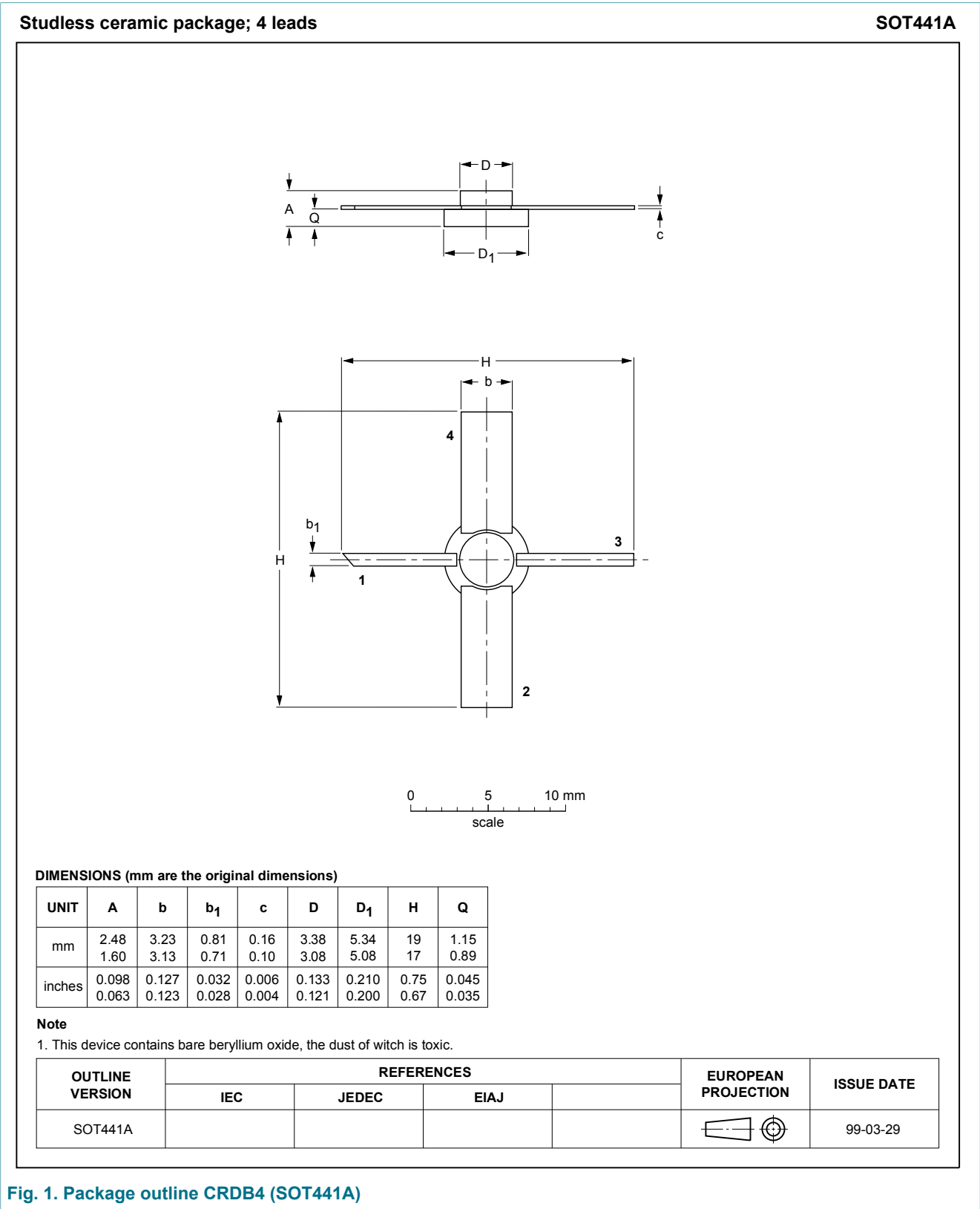
Terminal position code	R (radial)
Package type descriptive code	CRDB4
Package type industry code	CRDB4
Package style descriptive code	CRDB (ceramic radial disk-button)
Package style suffix code	NA (not applicable)
Package body material type	C (ceramic)
Mounting method type	S (surface mount)
Issue date	29-3-1999

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		3.08	-	3.23	3.38	mm
A	seated height		1.6	-	2.04	2.48	mm
n <sub>2</sub>	actual quantity of termination		-	-	4	-	



2. Package outline



### 3. Legal information

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